

RELIABILITY REPORT

FOR

MAX9257AGTL/V+ / MAX9257AGCM/V+

PLASTIC ENCAPSULATED DEVICES

January 24, 2012

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR. SUNNYVALE, CA 94086

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Quality Assurance	
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Conclusion

The MAX9257AGTL/V+ / MAX9257AGCM/V+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX9257A serializer pairs with the MAX9258A deserializer to form a complete digital video serial link. The MAX9257A/MAX9258A feature programmable parallel data width, parallel clock frequency range, spread spectrum, and preemphasis. An integrated control channel transfers data bidirectionally at power-up during video blanking over the same differential pair used for video data. This feature eliminates the need for external CAN or LIN interface for diagnostics or programming. The clock is recovered from input serial data at MAX9258A, hence eliminating the need for an external reference clock. The MAX9257A serializes 10, 12, 14, 16, and 18 bits with the addition of two encoding bits for AC-coupling. The MAX9258A deserializer links with the MAX9257A to deserialize a maximum of 20 (data + encoding) bits per pixel/parallel clock period for a maximum serial-data rate of 840Mbps. The word length can be adjusted to accommodate a higher pixel/parallel clock frequency. The pixel clock can vary from 5MHz to 70MHz, depending on the serial-word length. Enabling parity adds two parity bits to the serial word. The encoding bits reduce ISI and allow AC-coupling. The MAX9258A receives programming instructions from the electronic control unit (ECU) during the control channel and transmits to the MAX9257A over the serial video link. The instructions can program or update the MAX9257A, MAX9258A, or an external peripheral device, such as a camera. The MAX9257A communicates with the peripheral device with IÂ2C or UART. The MAX9257A/MAX9258A operate from a +3.3V core supply and feature separate supplies for interfacing to +1.8V to +3.3V logic levels. These devices are available in 40-lead TQFN or 48-pin LQFP packages. These devices are specified over the -40°C to +105°C temperature range.



II. Manufacturing Information

Programmable Serializer/Deserializer with UART/IÂ2C Control Channel A. Description/Function:

B. Process: **TS35** 87692 C. Number of Device Transistors: D. Fabrication Location: Taiwan

E. Assembly Location: China and Thailand Korea and Malaysia

F. Date of Initial Production: June 21, 2011

III. Packaging Information

A. Package Type: 40-pin TQFN 5x5 48-pin LQFP 7x7

B. Lead Frame: Copper Copper

C. Lead Finish: 100% matte Tin 100% matte Tin D. Die Attach: Conductive Conductive E. Bondwire: Au (1 mil dia.) Au (1 mil dia.) F. Mold Material: Epoxy with silica filler Epoxy with silica filler G. Assembly Diagram: #05-9000-2810 #05-9000-2924 Class UL94-V0 Class UL94-V0

I. Classification of Moisture Sensitivity per Level 1 Level 1

JEDEC standard J-STD-020-C

H. Flammability Rating:

J. Single Layer Theta Ja: 45°C/W °C/W °C/W K. Single Layer Theta Jc: 2°C/W L. Multi Layer Theta Ja: 28°C/W 46°C/W M. Multi Layer Theta Jc: 2°C/W 10°C/W

IV. Die Information

A. Dimensions: 117 X 117 mils

B. Passivation: Si₃N₄/SiO₂ (Silicon nitride/ Silicon dioxide)

C. Interconnect: AI/0.5%Cu D. Backside Metallization: None

E. Minimum Metal Width: Metal1 = 0.5 / Metal2-4 = 0.6 micron (as drawn)

F. Minimum Metal Spacing: Metal1 = 0.45 / Metal2-3 = 0.5 / Metal4 = 0.6 micron (as drawn)

G. Bondpad Dimensions:

H. Isolation Dielectric: SiO₂ I. Die Separation Method: Wafer Saw



V. Quality Assurance Information

A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)

Don Lipps (Manager, Reliability Engineering)

Bryan Preeshl (Vice President of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.

0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppmD. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \underbrace{\frac{1}{\text{MTTF}}}_{\text{MTTF}} = \underbrace{\frac{1.83}{192 \times 4340 \times 170 \times 2}}_{\text{(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)}$$

$$\lambda = 6.47 \times 10^{-9}$$

 $\lambda = 6.47 \text{ F.I.T.}$ (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the Process results in a FIT Rate of 0.11 @ 25C and 1.80 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing

The HS42 die type has been found to have all pins able to withstand a transient pulse of:

Latch-Up testing has shown that this device withstands a current of +/- 250mA and overvoltage per JEDEC JESD78 (lot QGFZFQ001E, D/C 1119).



Table 1

Reliability Evaluation Test Results

MAX9257AGTL/V+ / MAX9257ACGM/V+

= 135C	DC Parameters	90	0	QGFZFQ001F, D/C 1123
sed	& functionality	32	0	QGFZEQ001B, D/C 0823
ne = 192 hrs.		48	0	QGFZCQ001E, D/C 0742
	sed	sed & functionality	sed & functionality 32	sed & functionality 32 0

Note 1: Life Test Data may represent plastic DIP qualification lots.